

Product Change Notification / LIAL-04DLC0554

	Pre Change	Post Change
Pre and Post Change Summa	ry:	
		ditional assembly site for selected ATSAMA5D _FBGA (14x14x1.4mm) package.
•	•	es found in the Affected CPNs section. Itical files in two formats (.pdf and .xls)
PCN Type:Manufacturing Cha	nge	
PCN Status:Final Notification		
Notification Text:		
LIAL-04DLCO554_Affected_0 LIAL-04DLCO554_Affected_0		
Affected CPNs:	GDV 00440000 10	
		ditional assembly site for selected ATSAMA5D LFBGA (14x14x1.4mm) package.
Notification Subject:		
Manufacturing Change		
PCN Type:		
Microprocessors		
Product Category:		
11-Aug-2022		
Date:		

Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Amkor Technology Korea (K4), INC (ATK)			
Wire material	CuPdAu	CuPdAu	CuPdAu			
Die attach material	2100AS	2100AS	EP 2300			
Molding compound material	KE-G1250LKDS	KE-G1250LKDS	G770FE			
Substrate SM material	AUS308	AUS308	AUS308			
Substrate Core material	CCL-HL832NX(A-HS)	CCL-HL832NX(A-HS)	HL832NXAHS			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on-time delivery performance by qualifying ATK as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date: August 30, 2022 (date code: 2236)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2021				->	August 2022					
Workweek	4 0	41	42	4 3	4		32	3	3 4	35	36
Initial PCN Issue Date		Х									
Qual Report Availability								Х			
Final PCN Issue Date								Х			
Estimated Implementation Date											Х

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

October 07, 2021: Issued initial notification.

August 11, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 30, 2022. Revised the post change die attach material for ATK.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-04DLC0554 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

LIAL-04DLCO554 - CCB 4830 Final Notice: Qualification of ATK as an additional assembly site for selected ATSAMA5D26 and ATSAMA5D27 device families available in 289L LFBGA (14x14x1.4mm) package.

Affected Catalog Part Numbers (CPN)

ATSAMA5D26C-CU

ATSAMA5D27C-CU

ATSAMA5D26C-CN

ATSAMA5D27C-CN

ATSAMA5D26C-CNR

ATSAMA5D27C-CNR

ATSAMA5D26C-CNR01

ATSAMA5D26C-CUR

ATSAMA5D27C-CUR

Date: Thursday, August 11, 2022